

Advancements in Tracking Techniques for Future Circular Collider Experiments





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University and INFN Bari on behalf of the IDEA community



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Machine luminosity at e+e- colliders



Phase	Run duration	Center-of-mass	Integrated	Event	Extracted from	
	(years)	Energies (GeV)	Luminosity (ab^{-1})	Statistics	FCC CDR	
FCC-ee-Z	4	88-95 ±<100	КеV 150	3×10^{12} visible Z decays	LEP * 10 ⁵	
FCC-ee-W	2	158-162 <200	KeV 12	10 ⁸ WW events	LEP * 2.10 ³	
FCC-ee-H	3	240 ± 2 M	eV 5	10 ⁶ ZH events	Never done	
FCC-ee-tt	5	345-365 ±5м	eV 1.5	$10^6 t\bar{t}$ events	Never done	
s channel H	?	125 ± 2 м	eV 10?	5000 events	Never done	

Requirements of tracking system for an experiment at a leptonic collider

Central tracker system:

- state-of-the-art momentum and angular resolution for charged particles;
- > B field limited to \approx 2 T to contain the vertical emittance at Z pole. Large racking radius needed to improve momentum resolution.
- High transparency required given typical momenta in Z, H decays (far form the asymptotic limit where the Multiple Scattering contribution is negligible).
- Particle ID is a valuable additional ability.

Vertexing:

- excellent b- and c-tagging capabilities : few µm precision for charged particle origin;
- \succ small pitch, thin layers, limited cooling, first layer as close as possible to IP.

Challenges:

➢ Physics event rates up to 100 kHz (at Z pole) → strong requirements on sub-detectors and DAQ systems

Detector concepts for experiments at FCC-ee

IDEA

Instrumented return yoke **Double Readout Calorimeter**



- Well established design
 - ILC -> CLIC detector -> CLD •
- Full Si vtx + tracker:
- CALICE-like calorimetry;
- Large coil, muon system .
- Engineering still needed for operation with . continuous beam (no power pulsing)
 - Cooling of Si-sensors & calorimeters
- Possible detector optimizations
 - $\sigma_{\rm p}/p, \sigma_{\rm r}/E$
 - PID ($\mathcal{O}(10 \text{ ps})$ timing and/or RICH)?



- Si vtx detector; ultra light drift chamber w powerful PID; compact, light coil;
- Monolithic dual readout calorimeter;
 - Possibly augmented by crystal ECAL
- Muon system
- Very active community
 - Prototype designs, test beam campaigns, ...



- A design in its infancy
- Si vtx det., ultra light drift chamber (or Si)
- High granularity Noble Liquid ECAL as core
 - Pb/W+LAr (or denser W+LKr)
- CALICE-like or TileCal-like HCAL:
- Coil inside same cryostat as LAr, outside ECAL
- Muon system.
- Very active Noble Liquid R&D team
 - Readout electrodes, feed-throughs, electronics, light cryostat, ...
 - Software & performance studies

The IDEA detector at e⁺e⁻ colliders (1)

Innovative Detector for E+e- Accelerator

IDEA consists of:

a silicon pixel vertex detector Detector length 1300 cm etector height 1100 cm Preshower a large-volume extremely-**Dual Readout Calorimeter** light drift chamber surrounded by a layer of • DCH Rout = 200 cmsilicon micro-strip detectors DCH $z = \pm 200$ cm DCH Rin = 35 cma thin low-mass superconducting solenoid coil VTX a preshower detector based ٠ on µ-WELL technology Cal Rin = 250 cma dual read-out calorimeter ilicon wrapper Cal Rout = 450 cmmuon chambers inside the ٠ magnet return yoke, based

Magnet $z = \pm 300$ cm

Low field detector solenoid to maximize luminosity (to contain the vertical emittance at Z pole).

→ optimized at 2 T

on µ-WELL technology

→ large tracking radius needed to recover momentum resolution

Yoke 100 cm

Insubria U.+ Milano U. Vertex detector

ARCADIA prototype

Technology: Depleted Monolithic Active Pixel Sensors (DMAPS):

- \geq 25 x 25µm² pixel size for hit resolution ~ 3 µm
- $5 \mu m$ shown by ALICE ITS (30 mm pixels)
- > prototype with thickness ~ 200 μ m down to 50 μ m
- ➤ matrix 512x512
- low power consumption (< 20 mW/cm²)

Tests of different design options:

 IV and CV measurements of test-structures from the first and second production run: proven functionality, stable operation at full depletion, and good agreement with TCAD simulations



 $|V_{back}|$ [V]



A 2nd iteration prototype is working and will be tested soon at a test beam area



Silicon medium and outer tracker

ATLASPIX3 modules: a full-size system on chip, targeting the medium and outer tracker

- quad module, inspired by ATLAS ITk pixels
- pixel size $50 \times 150 \ \mu\text{m}^2$ ($25 \times 165 \ \mu\text{m}^2$ small size prototypes delivered) \geq
- reticle size 20x21 mm²
- TSI 180 nm process on 200 Ω cm substrate \geq
- 132 columns of 372 pixels \geq

Power consumption:

- ATLASPIX3 power consumption 150 mW/cm² \geq
- $600 \text{ mW/chip} \rightarrow 2.4 \text{ W/module} \rightarrow \text{total FE}$ \geq power 130 kW
- > additional power for on detector aggregation and de-randomizations ~2W/link



30µm

KIT+UK+IHEP+INFN

Complete system consists of 900'000 cm² area / 4 cm² chip = 225k chips (56k quad-modules):

- aggregation of several modules for data and services distribution is essential
- inner tracker will be 5-10% of this \geq

Data rate constrained by the inner tracker:

- \blacktriangleright average rate 10⁻⁴ 10⁻³ particles cm⁻² event⁻¹ at Z peak
- assuming 2 hits/particle, 96 bits/hit for ATLASPIX3 \geq
- See A. Andreazza talk for details 640 Mbps link/quad-module (assuming local module aggregation) provides ample operational margin

active smart" diode

depleted substrat

81/

- 16 modules can be arranged into 10 Gbps fast links: 3.5k links
- can also assume 100 Gbps links will be available: 350 links \geq

Design features of the IDEA Drift Chamber

INFN Bari and Lecce, IHEP + contributions from UCL, NWU and FSU

For the purpose of tracking and ID at low and medium momenta mostly for heavy flavour and Higgs decays, the IDEA drift chamber is designed to cope with:

- transparency against multiple scattering, more relevant than asymptotic resolution
- > a high precision momentum measurement
- an excellent particle identification and separation

Particle momentum range far from the asymptotic limit where MS is negligible



The Drift Chamber

The DCH is:

- a unique-volume, high granularity, fully stereo, low-mass cylindrical
- gas: He 90% iC₄H₁₀ 10%
- > inner radius $R_{in} = 0.35m$, outer radius $R_{out} = 2m$
- length L = 4m
- drift length ~1 cm
- drift time ~150ns
- \succ $\sigma_{xy} < 100 \ \mu\text{m}, \ \sigma_z < 1 \ \text{mm}$
- 12÷14.5 mm wide square cells, 5 : 1 field to sense wires ratio
- 112 co-axial layers, at alternating-sign stereo angles, arranged in 24 identical azimuthal sectors, with frontend electronics
- 343968 wires in total:

sense vires: 20 μ m diameter W(Au) = > 56448 wires field wires: 40 μ m diameter Al(Ag) = > 229056 wires f. and g. wires: 50 μ m diameter Al(Ag) = > 58464 wires

➤ the wire net created by the combination of + and orientation generates a more uniform equipotential surface
 → better E-field isotropy and smaller ExB asymmetries)



0.20 m

0.045 X



service area

F.E.E. included

➤ a large number of wires requires a non standard wiring procedure and needs a feed-through-less wiring system → a novel wiring procedure developed for the construction of the ultra-light MEG-II drift chamber

The Drift Chamber: Cluster Counting/Timing and PID

Principle: In He based gas mixtures the signals from each ionization act can be spread in time to few ns. With the help of a fast read-out electronics they can be identified efficiently.

> By counting the number of ionization acts per unit length (dN/dx), it is possible to identify the particles (P.Id.) with a better resolution w.r.t the dE/dx method.



• collect signal and identify peaks

• record the time of arrival of electrons generated in every ionisation cluster

reconstruct the trajectory at the most likely position

➤ Landau distribution of dE/dx originated by the mixing of primary and secondary ionizations, has large fluctuations and limits separation power of PID → primary ionization is a Poisson process, has small fluctuations

The cluster counting is based on replacing the measurement of an ANALOG information (the [truncated] mean dE/dX) with a DIGITAL one, the number of ionisation clusters per unit length:

dE/dx: truncated mean cut (70-80%), with a 2m track at 1 atm give $\sigma \approx 4.3\%$

 dN_{cl}/dx : for He/iC₄H₁₀=90/10 and a 2m track gives $\sigma_{dNcl/dx} / (dN_{cl}/dx) < 2.0\%$

The Drift Chamber: Cluster Counting/Timing and PID

of

sigma

10

9

8

7

Analitic

calculations

e/u $\mu/\tilde{\pi}$

 K/π

K/p

Particle Separation (dE/dx vs dN/dx)

dN/dx

dE/dx

- Analitic calculations: Expected excellent K/ π separation over the entire range except 0.85<p<1.05 GeV (blue lines)
- Simulation with Garfield++ and with the Garfield model ported in GEANT4:
 - the particle separation, both with dE/dx and with dN_{cl}/dx , in GEANT4 found considerably worse than in Garfield



11

signal box

Data reduction and pre-processing of drift chamber signals

Issue: with about 60000 drift cells, assuming to digitise the signal at 12 bits and 2 GS/s, a throughput of about 1 Tb/s is hardly sustainable by modern equipment \rightarrow is necessary to transfer all the data.

- with the cluster counting algorithms, by transferring only time and amplitude of each electron peak, these rates are reduced to about 60 Gb/s, resulting in a data reduction factor of more than one order of magnitude.
- Applying the cluster counting technique on FPGAs in real time has two main objectives:
 - 1. reduce transferred data
 - 2. reduce stored information
- A secondary advantage that allows us to reduce CPU usage during data analysis as the waveforms have already been analyzed in real time, saving only the necessary information

The objective of the new project is to implement, on a single FPGA, cluster counting algorithms for the parallel preprocessing of as many channels as possible in order to reduce the costs and complexity of the system and gain flexibility in determining the proximity correlations between hit cells for track segment search and for triggering purposes.

- For this purpose a card with multichannel reading is under development, testing different digitizers:
 - TEXAS INSTRUMENTS ADC32RF45 → → implementation of cluster counting almost complete
 - CAEN digitzer
 - NALU SCIENTIFIC ASoCv3 → test with native acquisition program and then implementation of the cluster counting





Silicon wrapper

In **IDEA** concept, tracking and PID provided by the DCH (+ VTX + medium and outer T)

- > Silicon wrapper for precise polar angle measurement
- \succ Good K-p separation from dE/dx except for p ~ 1 GeV
- Baseline: ATLASPIX3 modules BUT
- LGAD (Low-Gain Avalanche Diodes) with RSD (Resistive Silicon Detectors) technology are a possible option:
 - > TOF with excellent time resolution
 - Position from pixel-like geometry or charge sharing resistive-layer design



INFN Genova

Particle Separation (dE/dx vs dN/dx)



Reconstruction of the position from the signal distribution between contiguous electrodes

Need to show that LGAD could be produced with acceptable cost

- Technology developed by INFN Turin group, production by FBK
- External funding also (ERC, PRIN)

Muon detectors for IDEA: guiding principles

INFN Frascati, Ferrara, CERN

Future colliders experiments require extremely large muon detectors :

- \succ ~10000 m² in the barrel
- > 3-5000 m² in the endcap
- > 300 m² in the very forward region

PRESHOWER requirements:> high-spatial-resolution layer between magnet	 MUON CHAMBERS requirements: > low particle rate > rough resolution to detect muons behind 			
 and calorimeter charge measurement to help discriminating the electromagnetic nature of the clusters barrel + two endcaps 	 rough resolution to detect muons bennu the calorimeter with higher resolution could help detecting secondary vertices from Long- Lived Particles decaying into muons 			
 ✓ Efficiency > 98% ✓ Space Resolution < 100 µm ✓ Pitch = ~400 µm ✓ Strip capacitance ~70 pF ✓ 1.5 million channels ✓ FEE cost reduction —> custom ASIC ✓ Arranged in tiles 50x50 cm² ✓ Mass production —> T.T. 	 ✓ Efficiency > 98% ✓ Space Resolution < 400 µm ✓ Pitch = ~1.5 mm ✓ Strip capacitance ~270 pF ✓ ~5 million channels ✓ FEE cost reduction —> custom ASIC ✓ Arranged in tiles 50x50 cm² ✓ Mass production —> T.T. 			

The $\mu\text{-RWELL}$ detector schema

R&D on µ-RWELL technology mainly motivated by the wish of improving:

- ✓ the stability under heavy irradiation (discharge suppression)
- \checkmark the construction technology (simplifying the assembly)
- the technology transfer to industry (mass production)

The μ -RWELL is a Micro Pattern Gaseous Detector (MPGD) composed of only two elements: the μ -RWELL_PCB and the cathode.



- A WELL patterned kapton foil acting as amplification stage (GEM-like)
- a resisitive DLC layer (Diamond Like Carbon) for discharge suppression w/surface resistivity $\sim 50 \div 100 \text{ M}\Omega/\text{sq}$



M.Abbrescia

a standard readout PCB



Applying a suitable voltage between the top Cu-layer and the DLC the WELL acts as a multiplication channell for the ionization produced in the conversion/drift gas gap.



Test beam at CERN with μ-RWELL prototypes with

- 40cm long strips
- 0.4 mm strip pitch
- 1D readout

$\mu\text{-RWELL}$ test beam results and technology transfer







INF - DDG

Responsibility:

- Detector design (GERBER);
- Link with ELTOS
- Link with CERN-Rui
- Quality Control detector
- DLC Machine managment (>2023)

Elloz

Responsibility:

- PCB RWELL production
- Cathode production
- DLC+PCB RWELL coupling

CERN

Responsibility:

- PCB RWELL finalization
- Hot Electrical Cleaning
- Detector closure

Simulation and performance of the IDEA tracking system

A full standalone Geant4 (and partially DD4HEP) simulation of the Silicon Vertex (and Si wrapper), DriftChamber, DR Calorimeter and Muon Preshower



Summary/Conclusions

Advanced R&D effort on tracking detectors:

- vertex pixel detector, based on ARCADIA
- silicon medium and outer tracker, based on ATLASPIX3
- silicon wrapper, based on ATLASPIX3 (LGAD under evaluation)
- drift chamber design and cluster counting study, sinergy with MEG2
- muon chambers, synergy with LHCb upgrades

Plenty of areas for collaboration:

- detector design, construction, beam test, performance
- Iocal and global reconstruction, full simulation
- physics performance and impact
- ➢ etc.

Effort to build international collaboration on going (in some areas well advanced) and to be enforced

Manpower, funding under continuous discussion

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Backup

Machine luminosity for physics at e⁺e⁻ colliders



Phase	Run duration	Center-of-mass	Integrated	Event	
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FCC-ee-W	2	158-162	12	10 ⁸ WW events	
FCC-ee-H	3	240	5	10 ⁶ ZH events	
FCC-ee-tt	5	345-365	1.5	$10^6 t\overline{t}$ events	

- Higgs factory:
 - $10^6 e^+e^- \rightarrow HZ$
- EW & Top factory:
 - $3x10^{12} e^+e^- \rightarrow Z$
 - $10^8 \text{ e+e}^- \rightarrow \text{W}^+\text{W}^-$
 - $10^6 e^+e^- \rightarrow tt$

Flavor factory:

- $5x10^{12} \text{ e+e-} \rightarrow \text{bb, cc}$
- $10^{11} \text{ e+e-} \rightarrow \tau + \tau -$



Heav

Flavou

Physics requirements: Higgs, EWK and Heavy Flavour

Tracking:

- Momentum resolution for Z recoil (and $H \rightarrow \mu \mu$)
 - Comparatively low momenta involved \rightarrow transparency is important
- Vertex resolution/transparency to separate g, c, b, τ final states

Calorimetry:

- Jet-jet invariant mass resolution to separate W, Z, H in 2 jets
- Good π^0 ID for τ and HF reconstruction

EWK:

- Extreme definition of detector acceptance
- Extreme EM resolution (crystals) under study
 - Improved π^0 reconstruction
 - Physics with radiative return

Heavy Flavour:

PID to accurately classify final states and flavor tagging

The IDEA detector at e⁺e⁻ colliders (2)



- Tracking coverage \rightarrow 150 mrad \rightarrow No material in front of luminometer
- Calorimetry → 100 mrad

Goals of the IDEA tracking system:

- to preserve the momentum resolution for Z recoil (and $H \rightarrow \mu\mu$)
 - comparatively low momenta involved → transparency is important
- to preserve the vertex resolution/transparency to separate g, c, b, τ final states

Silicon medium and outer tracker



See F. Palla talk for details

Intermediate Tracker Barrel At 13 cm radius

22 staves of 8 modules each.

Lightweight reticular support structure (ALICE/Belle-II like)

Outer Tracker Barrel At 31.5 cm radius

51 staves of 16 modules each

Lightweight reticular support structure (ALICE/Belle-II like)

Design features: the Drift Chamber

Novel approach at construction technique of high granularity and high transparency Drift Chambers

Based on the MEG-II DCH new construction technique the IDEA DCH can meet these goals:

- Gas containment wire support functions separation: allows to reduce material to ≈ 10⁻³ X₀ for the inner cylinder and to a few x 10⁻² X₀ for the end-plates, including FEE, HV supply and signal cables
- Feed-through-less wiring:



allows to increase chamber granularity and field/sense wire ratio to reduce multiple scattering and total tension on end plates due to wires by using thinner wires



Chamber Layout (the IDEA drift chamber)

Radii (at z = 0)			Radii (at end plate)			
Inner Cylinder	350	mm	Inner Cylinder	350	mm	
Guard wires layer	354	mm	Guard wires layer	366	mm	
First active layer	356	mm	First active layer	369	mm	
Last (112 th) active layer	1915	mm	Last (112 th) active layer	1982	mm	
Guard wires layer	1927	mm	Guard wires layer	1995	mm	
Outer Cylinder	2000	mm	Outer Cylinder	2000	mm	

Active length	2000	mm		
Number of our on louons (0 louons)	(1.4.0) - 1.12		sense	56 448
Number of super-layers (8 layers)	(14x8) = 112		wires	
Number of sectors	24		field	
Number of cells per layer / per sector	192÷816 / 16		wires	284 256
Cell size (at z=0)	11.8 ÷ 14.9	mm	guard	2 016
2α angle	30°		wires	2 010
Stereo angle	43 ÷ 223	mrad	Total	342 720
Stereo drop	12.5 ÷ 68.0	mm	wires	

Wire Layout (the IDEA drift chamber)

- □ 112 co-axial layers (grouped in 14 superlayers of 8 layers each) of para-axial wires in 24 azimuthal sectors;
- □ stereo angles from ±43 mrad to ±223 mrad;
- rotational hyperboloid for each layer
- 192 (at inner layer), 816 (at outer layer) square drift cells (16 per sector);
- cell size ranging from 11.8 mm at the innermost layer, to 14.9 mm at the outermost one;
- □ ratio of field wires to sense wires = 5 : 1;
- 56 448 sense wires 284 256 field wires 2 016 guard wires;
- \Box sense wires 20 μ m diameter gold plated Mo (30 g tension);
- I field and guard wires, 40 and 50 μm diameter silver plated Al (30 g);
- La total wire tension 10 Ton.

Mechanical construction scheme

stress

Gas containment

Gas vessel can freely deform without affecting the internal wire position and mech. tension.



Wire support

Wire support structure not subject to differential pressure can be light and feed-through-less.



Plan for 2023/2024:

Analogy with MEG2 drift chamber



Static solution

On going: Finite element analysis in collaboration with a

350 MPa

company (EnginSoft) and Politecnico Un. in Turin.



End plates: 4-ply orthotropic (0-90-90-0) HM M30S 53 ET443 51% 60 µm/ply - 0.0053 g/cm² (0.021 g/cm² total)

Wire tension recovery scheme



construct a full-size prototype (4m long) to test different wire choices and the relative electrostatic stability and to validate the proposed tension recovery scheme of the endplates.

Gas Vessel (tentative procedure)

□ End-plate profile optimization

- Use isotropic material (1 mm thick Aluminum) solid rotational plates + inner cylinder (ideal joints)
- Assume infinitely rigid outer cylinder
- Parameterize geometry by:
 - constraining inner cylinder radius
 - constraining inner cylinder length
 - constraining outer cylinder radius
 - varying middle point of a 3 point-spline profile for the end plates
- Optimize dynamic properties:
 - minimum stress at inner boundary
 - minimum of maximum stress
 - maximum safety factor
- Replace isotropic material with light composite material
- Detailed FEM analysis
- □ Solve buckling instabilities
- □ Measure mechanical properties of chosen material
- Build a scale model and characterize it

Design features: the Drift Chamber

Novel approach at construction technique of high granularity and high transparency Drift Chambers

The solution adopted for MEG II:

- end-plates numerically machined from solid Aluminum (mechanical support only);
- Field, Sense and Guard wires placed azimuthally by a Wiring Robot with better than one wire diameter accuracy;
- wire PC board layers (green) radially spaced by numerically machined peek spacers (red) (accuracy < 20 µm);
- wire tension defined by homogeneous winding and wire elongation (ΔL = 100μm corresponds to ≈ 0.5 g);
- Drift Chamber assembly done on a 3D digital measuring table;
- build up of layers continuously checked and corrected during assembly;
- End-plate gas sealing done with glue.



(~ 12 wires/cm²) impossible to be built with a conventional technique based on feedthrough:



Cluster counting/timing performance

From the ordered sequence of the electrons arrival times, considering the average time separation between clusters and their time spread due to diffusion, reconstruct the most probable sequence of clusters drift times:

$$\begin{cases} t_i^{cl} \end{cases} \quad i = 1, N_{cl} \\ \frac{dE/dx}{} \end{cases}$$

$$\frac{S_{dE/dx}}{\left(dE/dx\right)} = 0.41 \times n^{-0.43} \times \left(L_{track}\left[m\right] \times P\left[atm\right]\right)^{-0.32}$$

from Walenta parameterization (1980)

truncated mean cut (70-80%) reduces the amount of collected information n = 112 and a 2m track at 1 atm give

$$\sigma \approx 4.3\%$$

Increasing P to 2 atm improves resolution by 20% ($\sigma \approx 3.4\%$) but at a considerable cost of multiple scattering contribution to momentum and angular resolutions.



 dN_{cl}/dx

$$\frac{S_{dN_{cl}/dx}}{\left(dN_{cl}/dx\right)} = \left(\mathcal{O}_{cl} \times L_{track}\right)^{-1/2}$$



 δ_{cl} = 12.5/cm for He/iC₄H₁₀=90/10 and a 2m track give

$$\sigma \approx 2.0\%$$

A small increment of iC_4H_{10} from 10% to 20% ($\delta_{cl} = 20$ /cm) improves resolution by 20% ($\sigma \approx 1.6\%$) at only a reasonable cost of multiple scattering contribution to momentum and angular resolutions.

Moreover, C.C. allows can improve the spatial resolution < 100 μ m for 8 mm drift cells in He based gas mixtures

07/30/2020

Silicon detectors for precision measurements:

- vertex detector/inner tracker (VTX)
- silicon medium and outer tracker
- silicon wrapper (SET)

+ design of the mechanical structure (light-weight staves)



Silicon wrapper

INFN Genua

- Low-Gain Avalanche Diodes (LGADs) are n-in-p silicon sensors
- Operated in low-gain regime (~ 20) controlled by the external bias
- > Critical electric field $E_c \sim 20 30 \text{ V/}\mu\text{m} \rightarrow \text{gain layer}$ region
- Detector ion resistive substrate (RSD) suitable for the si-Wrapper, combining tracking and TOF

The p⁺ dopant concentration of the gain implant gets reduced by irradiation and LGADs loose their multiplication power above $\sim 3\cdot 10^{15}\,n_{eq}/cm^2$

An innovative design of the gain implant has been designed to extend signal multiplication up to $\sim 10^{17}~n_{eq}/cm^2$

 \rightarrow Compensated LGAD

 \rightarrow A 3 years project has been accepted for funding by AIDAinnova as Blue Sky R&D to investigate and develop the compensated LGAD design



Silicon wrapper

INFN Genua

• Risoluzione Spaziale

- dipende da molti fattori: pitch, geometria degli elettrodi rumore dell'elettronica, digitalizzazione del segnale, algoritmo di ricostruzione...
- Si possono raggiungere risoluzioni pari a circa il 3% del pitch degli elettrodi

Risoluzione Temporale

- I sensori RSD mantengono le eccellenti caratteristiche di risoluzione temporale degli LGAD
- misura ottenuta dalla combinazione dei segnali distribuiti;
- contributo aggiuntivo dal ritardo di propagazione del segnale;
- ottima uniformità osservata sull'area attiva
- Test su fascio su geometrie della prima produzione hanno mostrato risoluzioni di 40-45 ps (~20 ps da test con laser)



The μ -RWELL: the detector architecture

The μ -RWELL is composed of only two elements: the μ -RWELL_POB and the cathode

The μ -RWELL_PCB, the core of the detector, is realized by coupling:

- 1. a WELL patterned kapton foil as amplification stage
- 2. a resistive layer^(*) for discharge suppression:
 - Single resistive layer (SRL) <100 kHz/cm²: single resistive layer → surface resistivity ~100 M O / □ (SHiP; CepC, Novosisbirsk, EIC, HIEPA)
 - Double resistive layer (DRL) >1 MHz/cm²: for LHCb-Muon upgrade
- 3. a standard readout PCB

(*) DLC = Diamond Like Carbon highly mechanical & chemical resistant



G. Bencivenni et al., 2015_JINST_10_P02008



The μ -RWELL: principle of operation

Applying a suitable voltage between the top Cu-layer and the DLC the WELL acts as a multiplication channell for the ionization produced in the conversion/drift gas gap.

Introduction of the resistive stage:

Pros: suppression of the transition from streamer to spark

 \rightarrow Spark amplitude reduction

Cons: reduction of the capability to stand high particle fluxes. But an appropriate grounding schemes of the resistive layer solves this problem







Comparison between the current drawn by a single GEM and a μ -RWELL at various **gas** gain.

The black spikes are the sparks in the detectors, clearly dumped in the μ -RWELL for higher gains

The μ -RWELL: overview of performance

Results with 2017 testbeam data at PSI lab



Plans for 2022/203

R&D for the 2022 foreseens the production of μ -RWELL with X-Y readout \rightarrow beamtest In October 2022 (SPS-H8-CERN)

Detector layouts 2D



These layouts allow to operate at lower gain with respect to the GEM detectors in «COMPASS»

Easy production technlogy for both layouts. Bi-dimensional space resolution to be verified with Beam Test

Technology transfer with ELTOS/CERN: flow chart

DLC sputtering with new INFN- CERN machine @ CERN



38

Step 1: producing μ-RWELL_PCB -with top patterned (pad/strip) -without bottom patterned

Step 2: DLC patterning -in ELTOS with BRUSHING-machine

Step 3: DLC foil gluing on PCB
-double 106-prepreg (~2x50 □m thick)
(already used in ELTOS)
-pre-smoothing + 106-prepreg (~50 µm thick)
-single 1080-prepreg (~75 µm thick)

Step 4: top copper patterning

Step 5: Kapton etching on small PCB





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Technology transfer with ELTOS/CERN: flow chart



Responsibility:

- Detector design (GERBER);
- Link with ELTOS
- Link with CERN-Rui
- Quality Control detector
- DLC Machine managment (>2023)



Responsibility:

- PCB RWELL production
- Cathode production
- DLC+PCB RWELL coupling



Responsibility:

- PCB RWELL finalization
- Hot Electrical Cleaning
- Detector closure

